

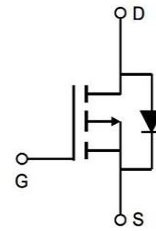
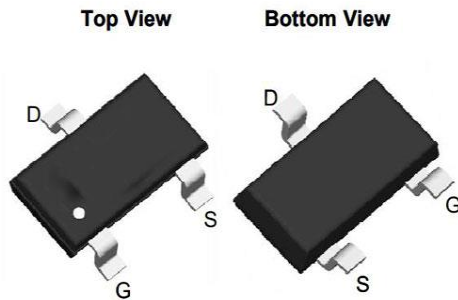
**General Description**

-30V /-2.6A Single P Power MOSFET

 Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5\text{ V}$ 

Pb-free lead plating; RoHS compliant

$V_{DS}$	-30	V
$R_{DS(on),TYP@VGS=10V}$	105.0	m $\Omega$
$R_{DS(on),TYP@VGS=4.5}$	165.0	m $\Omega$
$I_D$	-2.6	A



Part ID	Package Type	Marking	Tape and reel information
AC2301	SOT23-3	2301	3000


 100% UIS Tested  
 100% kg tested

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	12	$\pm V$
Continuous Drain Current <sup>A</sup>	$I_D$	$T_A=25^\circ C$	-2.6
		$T_A=70^\circ C$	-2.2
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	-4.2	A
Avalanche Current <sup>G</sup>	$I_{AR}$	-0.8	
Repetitive avalanche energy $L=0.1\text{mH}$ <sup>G</sup>	$E_{AR}$	-1.9	mJ
Power Dissipation <sup>A</sup>	$P_D$	$T_A=25^\circ C$	1.4
		$T_A=70^\circ C$	0.9
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	375	562	$^\circ C/W$
Maximum Junction-to-Ambient <sup>A</sup>				
Maximum Junction-to-Lead <sup>c</sup>	$R_{\theta JL}$	225	360	$^\circ C/W$

**STATIC PARAMETERS**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = -250uA, V <sub>GS</sub> = 0V	-30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V			-1	uA
					-5	
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 250μA	-0.7	-1.1	-1.4	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-2.6A		105.0	150.0	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2.6A		165.0	214.5	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2.6A		63		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V		-0.72	-1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				-2.6	A

**DYNAMIC PARAMETERS**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, f=1MHz		260	317	pF
C <sub>oss</sub>	Output Capacitance			37	45	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			20	23	pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz			0.5	Ω

**SWITCHING PARAMETERS**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, I <sub>D</sub> =-2.6A		2.8		nC
Q <sub>g</sub> 4.5V)	Total Gate Charge			1.4		
Q <sub>gs</sub>	Gate Source Charge			0.7		
Q <sub>gd</sub>	Gate Drain Charge			1		
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>L</sub> =0.75 Ω, R <sub>GEN</sub> =3Ω		5.75		ns
t <sub>r</sub>	Turn-On Rise Time			4.6		
t <sub>D(off)</sub>	Turn-Off DelayTime			16.1		
t <sub>f</sub>	Turn-Off Fall Time			5.175		
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =-8A, dI/dt=500A/μs		11.5		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =18A, dI/dt=500A/μs		4.5		nC

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

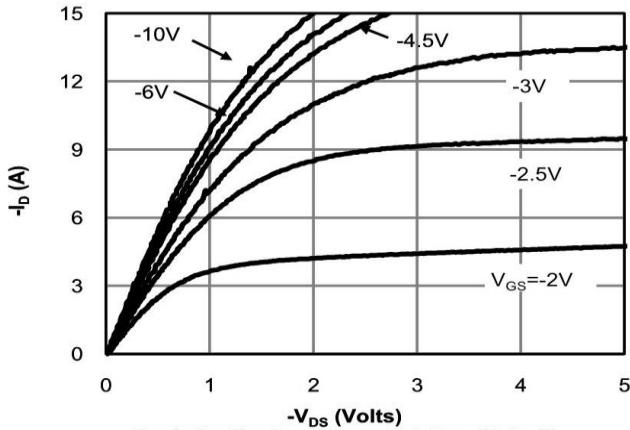


Fig 1: On-Region Characteristics (Note E)

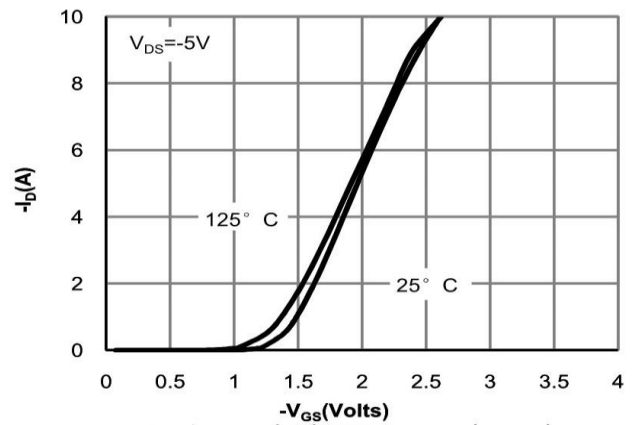


Figure 2: Transfer Characteristics (Note E)

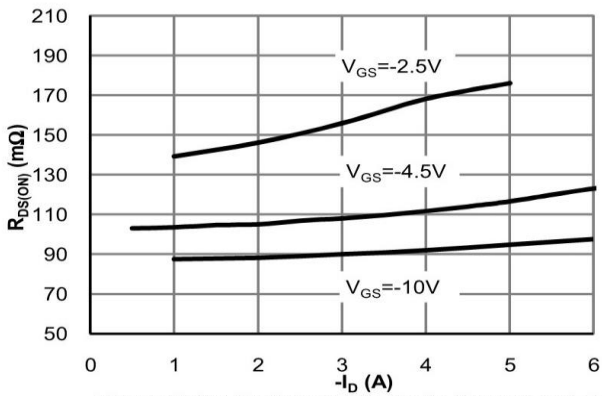


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

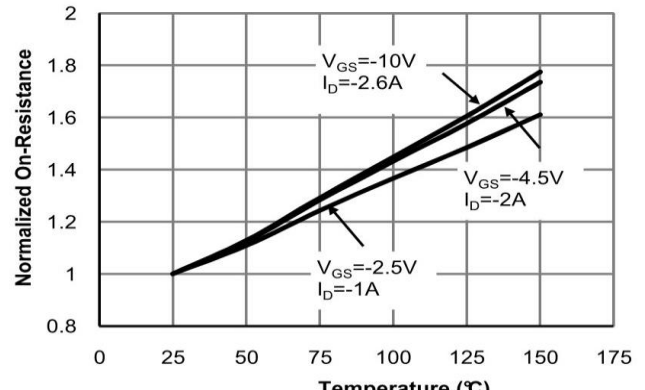


Figure 4: On-Resistance vs. Junction Temperature (Note E)

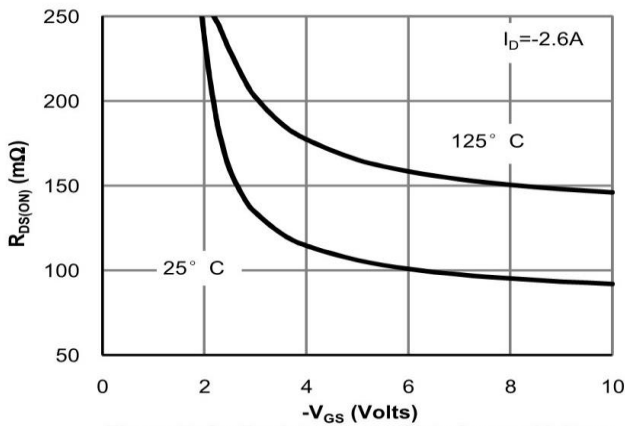


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

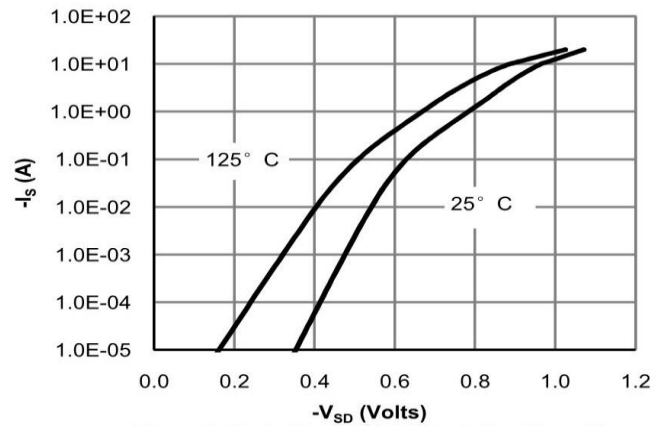


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

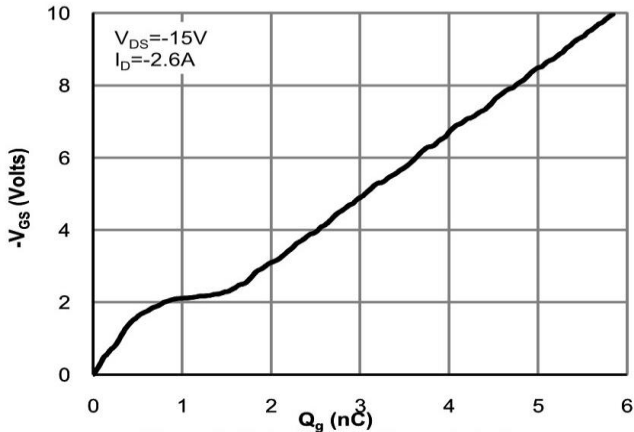


Figure 7: Gate-Charge Characteristics

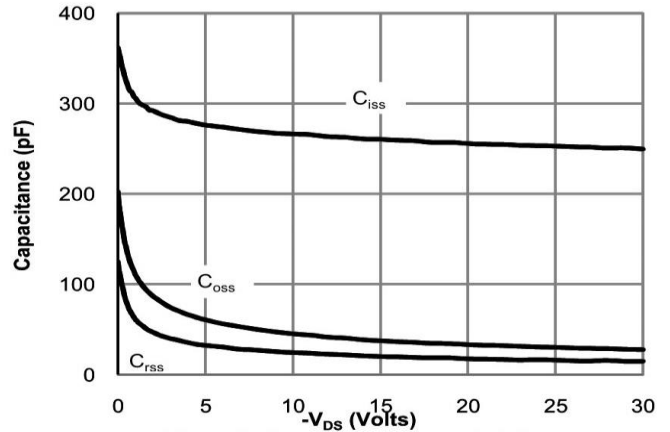


Figure 8: Capacitance Characteristics

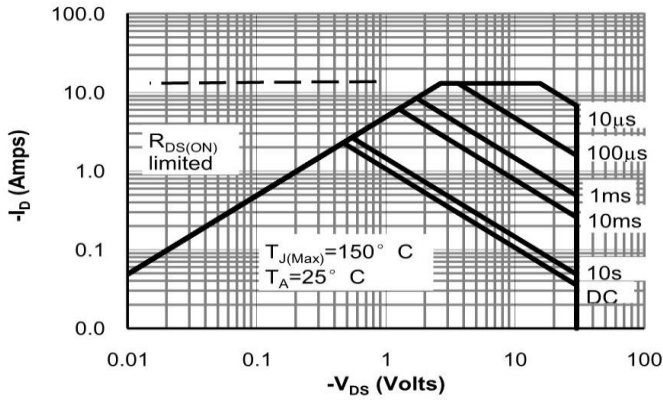


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

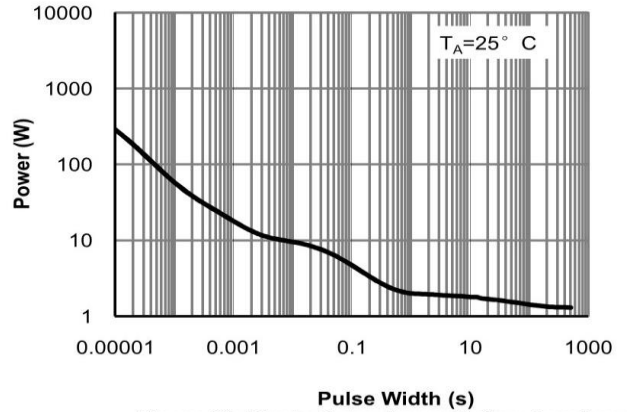


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

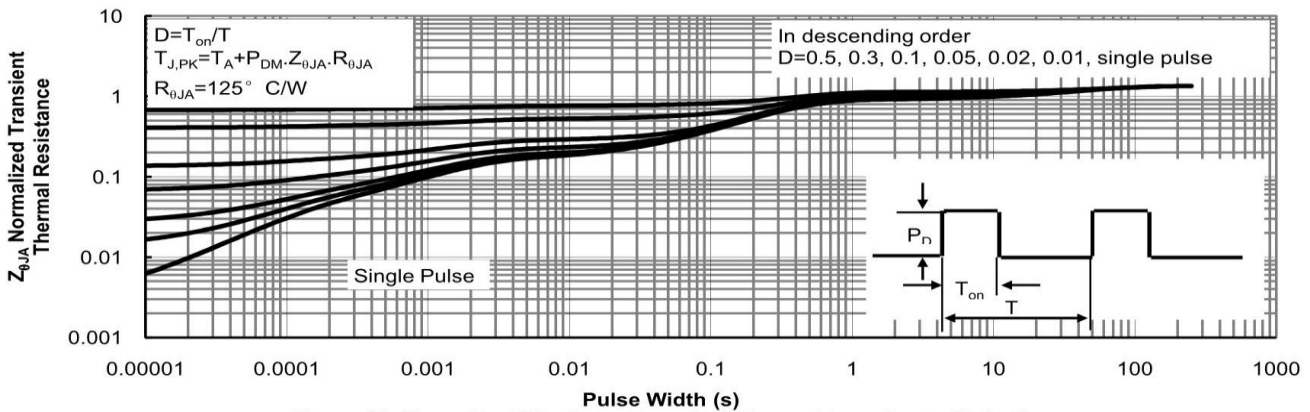


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)